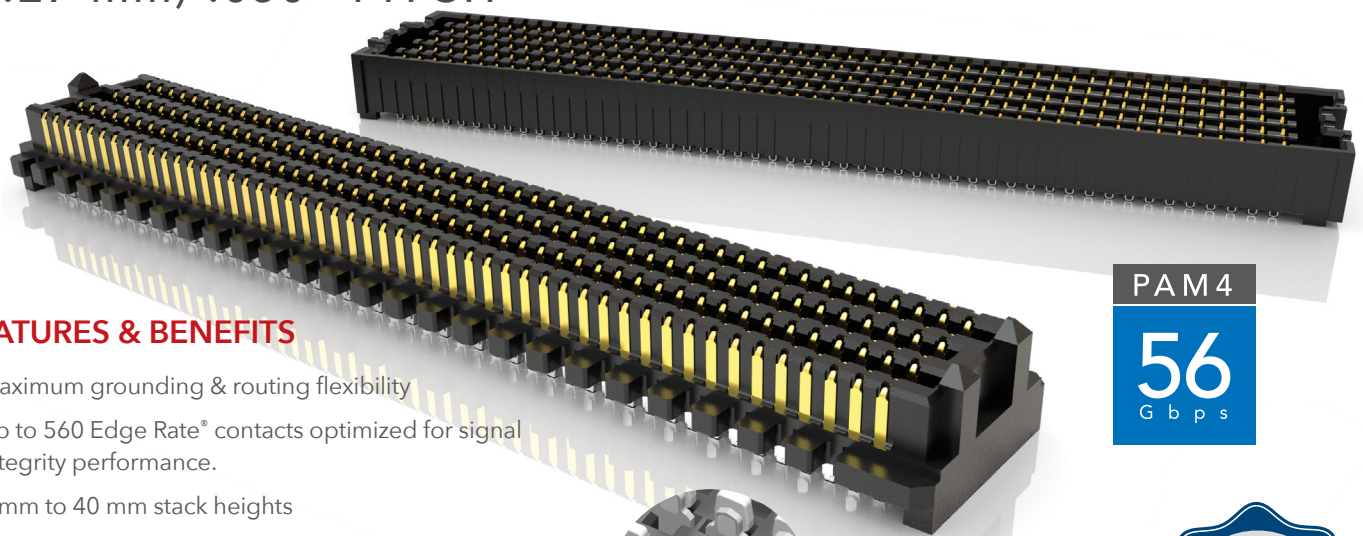




HIGH-DENSITY OPEN-PIN-FIELD ARRAYS

(1.27 mm) .050" PITCH

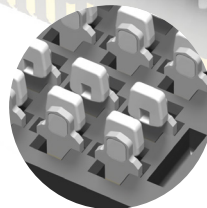


FEATURES & BENEFITS

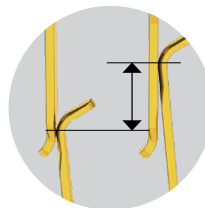
- Maximum grounding & routing flexibility
- Up to 560 Edge Rate® contacts optimized for signal integrity performance.
- 7 mm to 40 mm stack heights
- Variety of designs and options: Right-Angle, Guide Posts, 85 Ω Elevated Risers, 85 Ω Tuned, Press-Fit and Press-Fit Right-Angle, Guide Post Field Termination Kits
- Cable mates (SEAC Series) and Jack Screw Standoffs (JSO Series) also available
- Standards: VITA™ 47, VITA™ 57.1 FMC™, VITA™ 57.4 FMC™+, VITA™ 74 VNX™, PISMO™ 2
- Supports high-speed protocols such as Ethernet, PCI Express®, Fibre Channel & InfiniBand™
- Severe Environment Testing qualified (SEAM/SEAF); aligns with MIL-DTL-55302. Visit samtec.com/set

VITA/VNX/VNX+/FMC/FMC+/XMC/XMC+ are all respective trademarks of VITA PCI-SIG®.

The PCI Express® design marks are registered trademarks and/or service marks of PCI-SIG.



Solder Charges



(1.12 mm) .044"
Nominal Wipe

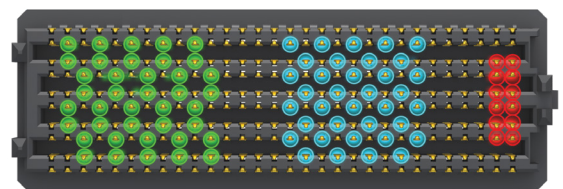
**EDGE
RATE®**
CONTACT

PAM 4

56
G b p s



MAXIMUM GROUNDING & ROUTING FLEXIBILITY



Differential Pair

Single-Ended

Power

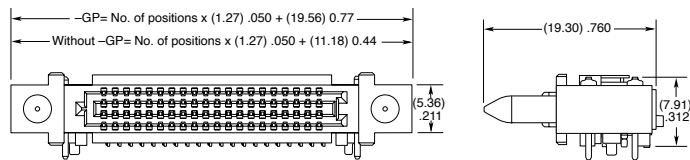
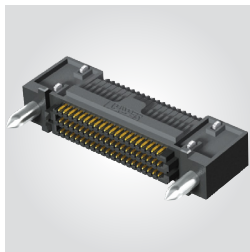
SERIES	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING	LEAD-FREE SOLDERABLE
SEAM/SEAF	Black LCP	Copper Alloy	Au or Sn over 50 μ " (1.27 μ m) Ni	-55 °C to +125 °C	2.7 A (10 pins powered)	240 VAC/339 VDC	Yes
SEAM-RA/SEAF-RA	Black LCP	Copper Alloy	Au or Sn over 50 μ " (1.27 μ m) Ni	-55 °C to +125 °C	1.9 A (10 pins powered)	240 VAC/339 VDC	Yes
SEAM-GP	Black LCP	Copper Alloy	Au or Sn over 50 μ " (1.27 μ m) Ni	-55 °C to +125 °C	2.7 A (10 pins powered)	240 VAC/339 VDC	Yes
SEAMP/SEAFP	Natural High Temp Nylon	Copper Alloy (SEAMP) BeCu Alloy (SEAFP)	Au or Sn over 50 μ " (1.27 μ m) Ni	-55 °C to +125 °C	1.9 A (6 pins powered)	255 VAC/361 VDC	Not Available
SEAR	Black LCP	Hard Gold Plated	Au over 50 μ " (1.27 μ m) Ni	-55 °C to +125 °C	1.4 A (20 pins powered)	240 VAC/339 VDC	Not Available
SEAMI	Black LCP	Copper Alloy	Au or Sn over 50 μ " (1.27 μ m) Ni	-55 °C to +125 °C	Not Available	Not Available	Yes

Note: Some lengths, styles and options are non-standard, non-returnable

SERIES	POSITIONS PER ROW	01	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	RA	OPTIONS	"X"R
SEAM Right-Angle Terminal	-20 -30		-L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on solder tail	-04 -06 -08 -10	-1 = Tin/Lead Alloy Solder Charge		-GP = Guide Post/Hole	-TR = Tape & Reel
SEAF Right-Angle Socket	-40 -50		-S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on solder tail	-08 & -10 Row options require fixturing to process	-2 = Lead-Free Solder Charge		-K = Polyimide Film Pick & Place Pad	-FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)
							-LP Latch Post (Available with SEAF in -06 Row with 30 positions only; Required for mating to SEAC)	

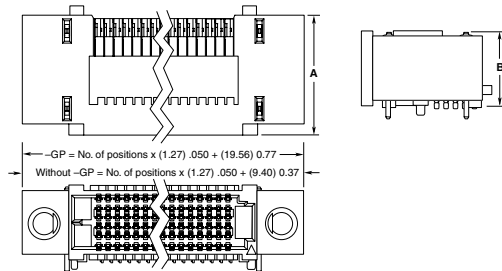
SEAM-RA

Board Mates:
SEAF, SEAF-RA, SEAFP



SEAF-RA

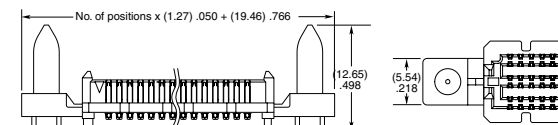
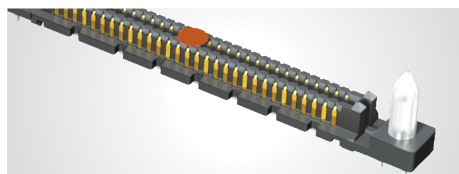
Board Mates:
SEAM, SEAMP



NO. PINS PER ROW	A	B
-04	(13.77) .542	(7.91) .311
-06	(16.31) .642	(10.45) .411
-08	(18.85) .742	(12.99) .511
-10	(21.39) .842	(15.53) .611

View complete specifications at: samtec.com?SEAM-RA & samtec.com?SEAF-RA

SERIES	POSITIONS PER ROW	02.0	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	A	GP	K	"X"R
SEAM Terminal with Guide post	-20, -30, -40, -50		-L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on solder tail	-04 -06 -08 -10	-1 = Tin/Lead Alloy Solder Charge				-TR = Tape & Reel
SEAM-GP			-S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on solder tail		-2 = Lead-Free Solder Charge				-FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)



Note: Some lengths, styles and options are non-standard, non-returnable

View complete specifications at: samtec.com?SEAM